

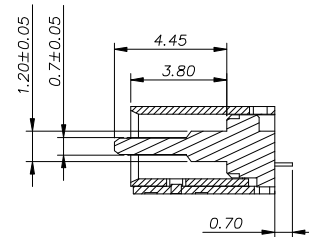
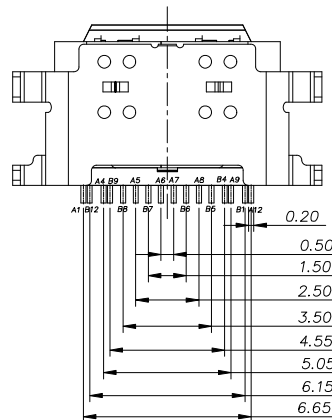
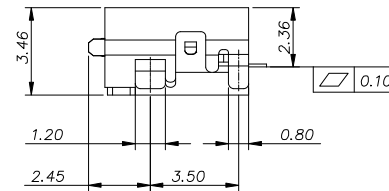
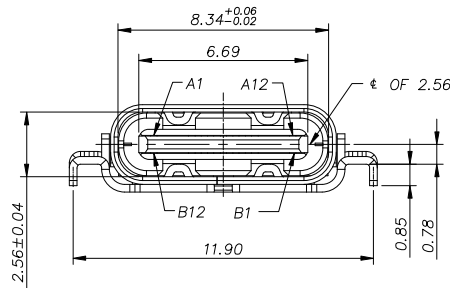
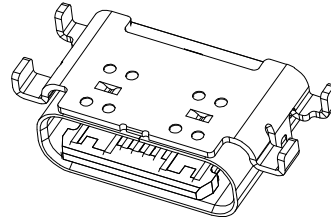
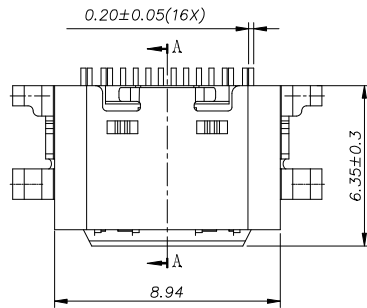
RoHS

MAPX

MODIFICATION

DRW

DATE



SECTION: A-A

NOTE:

1.MATERIAL SPECIFICATION:

- 1.HOUSING: LCP_BLACK,UL94 V-0.
- 2.CONTACTS: COPPER ALLOY
- 3.MID PLATE: STAINLESS STEEL(SUS301)
- 4.FRONT SHELL: STAINLESS STEEL(SUS304)
- 5.COVER: STAINLESS STEEL(SUS304)

2.PLATING SPECIFICATION:

2-1.CONTACTS:

- Ni 50u" MIN. UNDER PLATED OVER ALL.
- Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
- (GOLD PLATING THICKNESS FOLLOW THE P/N)
- PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N

2-2.FRONT SHELL & COVER:

- Ni 30u" MIN. UNDER PLATED OVER ALL.

2-3.MID PLATE:

- CLEAR ONLY

3.MECHANICAL PERFORMANCE,

- 3-1.INSERTION FORCE: 0.5~2.0kgf.
- 3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
- 3-3.DURABILITY: 10000 CYCLES.

4.ELECTRICAL PERFORMANCE,

- 4-1. CURRENT RATING: 3.0A
VOLTAGE RATING: 5.0V
- 4-2. LLCR:
VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.
SHIELD: 50mΩ/MAX.
LLCR MAX. CHANGE OF ALL PINS: 10mΩ
- 4-3.INSULATION RESISTANCE: 100MΩ MIN
- 4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.

5. ENVIRONMENTAL PERFORMANCE:

- OPERATING TEMPERATURE: -25°C~+85°C.

6.IR REFLOW:

- THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.

产品图

PRODUCT CHART DWG

公差一览表

TOLERANCE UNLESS OTHERWISE

X.	±0.25	X.	±5.*
.X	±0.20	.X	±2.*
.XX	±0.15	.XX	±1.*
.XXX	±0.05	.XXX	±0.5*

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单位	MM	制图	L S S	制图料号	C918-EC418K2024S40011
比例	1:1	审核	GT	产品名称	TYPE-C3.1 16PF SMT沉板
日期	2020-05-22	核准	GR	角法	0.8母座不锈钢单排短体L6.35
DATE		角法	VIEW	版本	AO